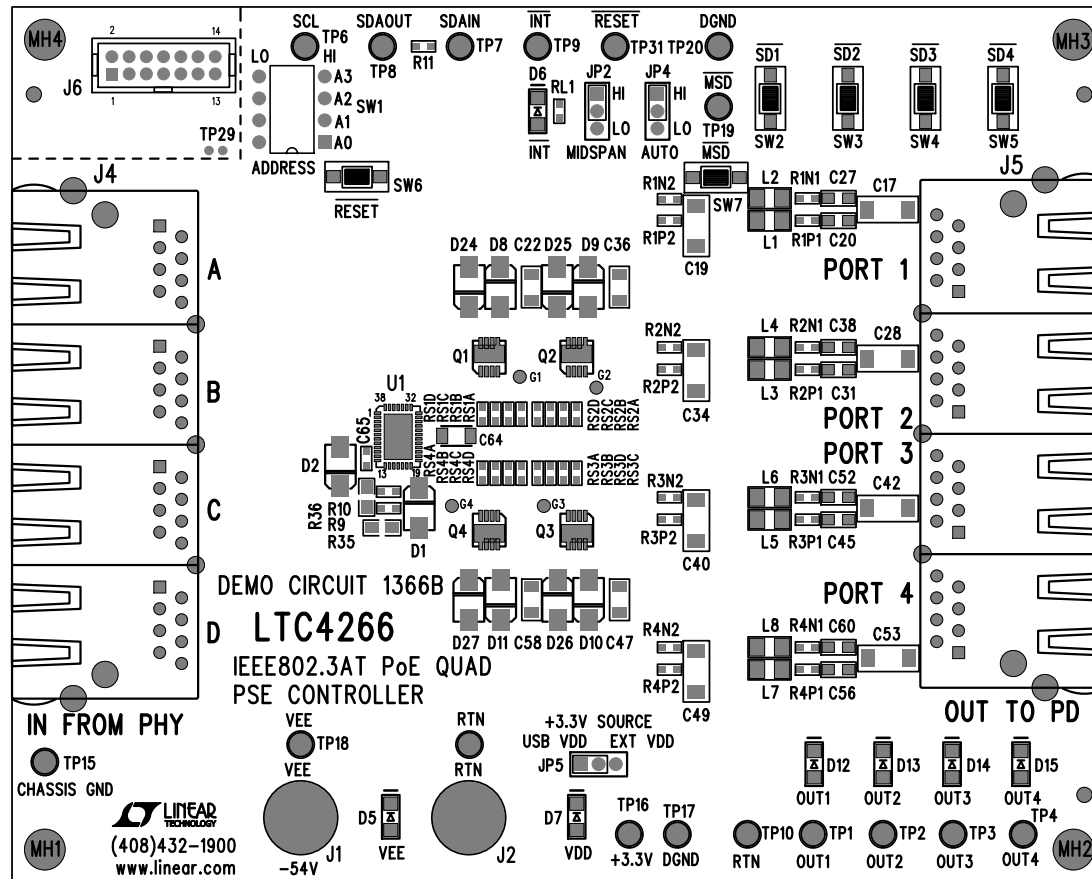
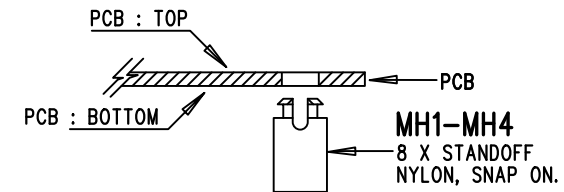


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	REBUILD WITH CHANGE	DILIAN R.	08-11-15



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AS SHOWN BELOW:



APPROVALS		LINEAR TECHNOLOGY		
PCB DES.	KIM T.	1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY		
APP ENG.	DILIAN R.			
		TITLE: TOP ASSEMBLY DRAWING		
		IEEE802.3AT PoE QUAD PSE CONTROLLER		
		SIZE	IC NO.	REV.
		N/A	LTC4266CUHF DEMO CIRCUIT 1366B	2
SCALE = NONE		FILENAME: DC1366B-2.PCB		SHT 1 OF 2